



## Materials Declaration

<b>Package</b>	CSP BGA
<b>Body Size</b>	7 X 7
<b>Ball Count</b>	32
<b>Option</b>	SnPb

### Ceramic

Item	% of Ceramic	Weight (g)	PPM
Alumina	91.22	2.99 E-01	671033
Chromium oxide	3.89	1.28 E-02	28616
Silicon dioxide	3.62	1.19 E-02	26629
Titanium dioxide	1	3.28 E-03	7356
Molybdenum	0.27	8.85 E-04	1986

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

### Solder Seal

Item	% of Solder Seal	Weight (g)	PPM
Lead	91.14	4.01 E-03	8999
Tin	6.33	2.79 E-04	625
Silver	1.27	5.59 E-05	125
Indium	1.26	5.54 E-05	124

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

### Pads

Item	% of Pads	Weight (g)	PPM
Tungsten	83.55	2.06 E-02	46124
Nickel	10.71	2.63 E-03	5912
Gold	5.74	1.41 E-03	3169

Item	PPM	Method
Pb		
Cd		
Hg		
Cr+6		
PBB		
PBDE		

### Die Mount

Item	% of Die Mount	Weight (g)	PPM
Polyimide	94.5	3.69 E-04	827
Silicon dioxide	5.5	2.15 E-05	48

### Chip

Item	% of Chip	Weight (g)	PPM
Chip	100	1.90 E-02	42638

### Wire

Item	% of Wire	Weight (g)	PPM
Aluminum	99	5.94 E-05	133
Silicon	1	6.00 E-07	1

### Metal Lid

Item	% of Metal Lid	Weight (g)	PPM
Nickel	42.45	2.17 E-02	48755
Iron	57.55	2.95 E-02	66098

### Solder Balls

Item	% of Solder Balls	Weight (g)	PPM
Sn	63	1.15 E-02	25703
Pb	37	6.73 E-03	15095

### Package Totals

Weight (g)	PPM
4.46 E-01	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge  
 ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information

12/23/05



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